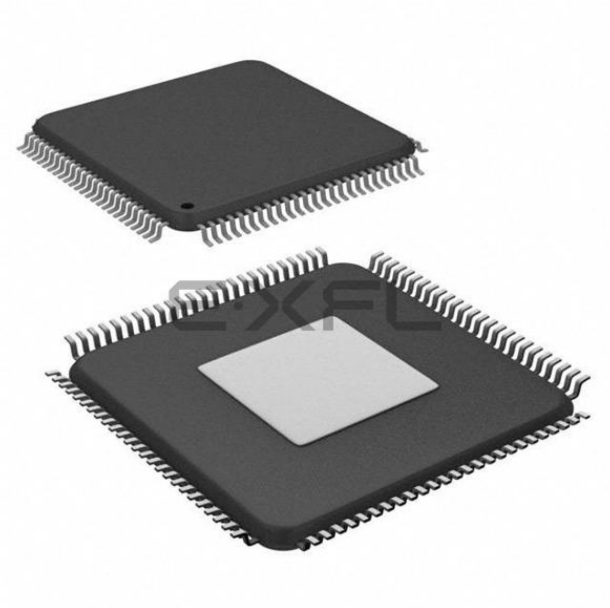

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	144MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, LINbus, MMC/SD, SPI, UART/USART, USB OTG, USIC
Peripherals	DMA, I²S, LED, POR, Touch-Sense, WDT
Number of I/O	75
Program Memory Size	2MB (2M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	352K x 8
Voltage - Supply (Vcc/Vdd)	3.13V ~ 3.63V
Data Converters	A/D 24x12b; D/A 2x12b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP Exposed Pad
Supplier Device Package	PG-LQFP-100-25
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xmc4700f100k2048aaxqma1

On-Chip Memories

- 16 KB on-chip boot ROM
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- 2,048 KB on-chip Flash Memory with 8 KB instruction cache

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- Ethernet MAC module capable of 10/100 Mbit/s transfer rates
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- Controller Area Network interface (MultiCAN), Full-CAN/Basic-CAN with 6 nodes, 256 message objects (MO), data rate up to 1 MBaud
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- SD and Multi-Media Card interface (SDMMC) for data storage memory cards
- External Bus Interface Unit (EBU) enabling communication with external memories and off-chip peripherals

Analog Frontend Peripherals

- Four Analog-Digital Converters (VADC) of 12-bit resolution, 8 channels each, with input out-of-range comparators
- Delta Sigma Demodulator with four channels, digital input stage for A/D signal conversion
- Digital-Analog Converter (DAC) with two channels of 12-bit resolution

Industrial Control Peripherals

- Two Capture/Compare Units 8 (CCU8) for motor control and power conversion
- Four Capture/Compare Units 4 (CCU4) for use as general purpose timers
- Two Position Interfaces (POSIF) for servo motor positioning
- Window Watchdog Timer (WDT) for safety sensitive applications
- Die Temperature Sensor (DTS)
- Real Time Clock module with alarm support
- System Control Unit (SCU) for system configuration and control

Input/Output Lines

- Programmable port driver control module (PORTS)
- Individual bit addressability

Table 2 Features of XMC4[78]00 Device Types (cont'd)

Derivative[1)]	LED TS Intf.	SD MMC Intf.	EBU Intf.[2)]	ETH Intf. [3)]	ECAT Slave Intf.	USB Intf.	USIC Chan.	MultiCAN Nodes, MO
XMC4800-E196x2048	1	1	SDM	MR	2 x MII	1	3 x 2	N[0..5] MO[0..255]
XMC4800-F144x2048	1	1	SDM	MR	2 x MII	1	3 x 2	N[0..5] MO[0..255]
XMC4800-F100x2048	1	1	M16	R	2 x MII	1	3 x 2	N[0..5] MO[0..255]
XMC4800-E196x1536	1	1	SDM	MR	2 x MII	1	3 x 2	N[0..5] MO[0..255]
XMC4800-F144x1536	1	1	SDM	MR	2 x MII	1	3 x 2	N[0..5] MO[0..255]
XMC4800-F100x1536	1	1	M16	R	2 x MII	1	3 x 2	N[0..5] MO[0..255]
XMC4800-E196x1024	1	1	SDM	MR	2 x MII	1	3 x 2	N[0..5] MO[0..255]
XMC4800-F144x1024	1	1	SDM	MR	2 x MII	1	3 x 2	N[0..5] MO[0..255]
XMC4800-F100x1024	1	1	M16	R	2 x MII	1	3 x 2	N[0..5] MO[0..255]

1) x is a placeholder for the supported temperature range.
2) Memory types supported S=SDRAM, D=DEMUX, M=MUX 16-bit and 32-bit, M16=MUX 16-bit
3) Supported interfaces, M=MII, R=RMII.

Table 3 Features of XMC4[78]00 Device Types

Derivative[1)]	ADC Chan.	DSD Chan.	DAC Chan.	CCU4 Slice	CCU8 Slice	POSIF Intf.
XMC4700-E196x2048	32	4	2	4 x 4	2 x 4	2
XMC4700-F144x2048	32	4	2	4 x 4	2 x 4	2
XMC4700-F100x2048	24	4	2	4 x 4	2 x 4	2
XMC4700-E196x1536	32	4	2	4 x 4	2 x 4	2
XMC4700-F144x1536	32	4	2	4 x 4	2 x 4	2
XMC4700-F100x1536	24	4	2	4 x 4	2 x 4	2
XMC4800-E196x2048	32	4	2	4 x 4	2 x 4	2

Table 3 Features of XMC4[78]00 Device Types (cont'd)

Derivative[1)]	ADC Chan.	DSD Chan.	DAC Chan.	CCU4 Slice	CCU8 Slice	POSIF Intf.
XMC4800-F144x2048	32	4	2	4 x 4	2 x 4	2
XMC4800-F100x2048	24	4	2	4 x 4	2 x 4	2
XMC4800-E196x1536	32	4	2	4 x 4	2 x 4	2
XMC4800-F144x1536	32	4	2	4 x 4	2 x 4	2
XMC4800-F100x1536	24	4	2	4 x 4	2 x 4	2
XMC4800-E196x1024	32	4	2	4 x 4	2 x 4	2
XMC4800-F144x1024	32	4	2	4 x 4	2 x 4	2
XMC4800-F100x1024	24	4	2	4 x 4	2 x 4	2

1) x is a placeholder for the supported temperature range.

1.4 Definition of Feature Variants

The XMC4[78]00 types are offered with several memory sizes and number of available VADC channels. **Table 4** describes the location of the available Flash memory, **Table 5** describes the location of the available SRAMs, **Table 6** the available VADC channels.

Table 4 Flash Memory Ranges

Total Flash Size	Cached Range	Uncached Range
1,024 Kbytes	$0800\ 0000_H$ – $080F\ FFFF_H$	$0C00\ 0000_H$ – $0C0F\ FFFF_H$
1,536 Kbytes	$0800\ 0000_H$ – $0817\ FFFF_H$	$0C00\ 0000_H$ – $0C17\ FFFF_H$
2,048 Kbytes	$0800\ 0000_H$ – $081F\ FFFF_H$	$0C00\ 0000_H$ – $0C1F\ FFFF_H$

Table 10 Package Pin Mapping (cont'd)

Function	LFBGA-196	LQFP-144	LQFP-100	Pad Type	Notes
P5.3	L10	81	-	A2	
P5.4	M10	80	-	A2	
P5.5	L8	79	-	A2	
P5.6	M8	78	-	A2	
P5.7	L7	77	55	A1+	
P5.8	K6	58	-	A2	
P5.9	M6	57	-	A2	
P5.10	K5	56	-	A1+	
P5.11	L5	55	-	A1+	
P6.0	J10	101	-	A2	
P6.1	H9	100	-	A2	
P6.2	K10	99	-	A2	
P6.3	J9	98	-	A1+	
P6.4	H10	97	-	A2	
P6.5	H11	96	-	A2	
P6.6	H12	95	-	A2	
P7.0	L13	-	-	A2	
P7.1	M13	-	-	A2	
P7.2	N13	-	-	A2	
P7.3	M14	-	-	A2	
P7.4	N14	-	-	A1+	
P7.5	L14	-	-	A1+	
P7.6	K14	-	-	A1+	
P7.7	J14	-	-	A1+	
P7.8	H14	-	-	A2	
P7.9	G13	-	-	A1+	
P7.10	G14	-	-	A1+	
P7.11	F14	-	-	A1+	
P8.0	B7	-	-	A2	
P8.1	A7	-	-	A2	
P8.2	B3	-	-	A2	
P8.3	B2	-	-	A2	
P8.4	B6	-	-	A1+	

Table 10 Package Pin Mapping (cont'd)

Function	LFBGA-196	LQFP-144	LQFP-100	Pad Type	Notes
P8.5	B5	-	-	A1+	
P8.6	A2	-	-	A1+	
P8.7	B4	-	-	A1+	
P8.8	A3	-	-	A2	
P8.9	A5	-	-	A1+	
P8.10	A4	-	-	A1+	
P8.11	A6	-	-	A1+	
P9.0	F13	-	-	A2	
P9.1	E14	-	-	A2	
P9.2	D14	-	-	A1+	
P9.3	D13	-	-	A2	
P9.4	A12	-	-	A1+	
P9.5	A11	-	-	A1+	
P9.6	B11	-	-	A1+	
P9.7	A9	-	-	A1+	
P9.8	A8	-	-	A1+	
P9.9	A10	-	-	A1+	
P9.10	B8	-	-	A1+	
P9.11	B9	-	-	A1+	
P14.0	N3	42	31	AN/DIG_IN	
P14.1	N2	41	30	AN/DIG_IN	
P14.2	M3	40	29	AN/DIG_IN	
P14.3	L4	39	28	AN/DIG_IN	
P14.4	M1	38	27	AN/DIG_IN	
P14.5	M2	37	26	AN/DIG_IN	
P14.6	L3	36	25	AN/DIG_IN	
P14.7	L2	35	24	AN/DIG_IN	
P14.8	P5	52	37	AN/DAC/DIG_IN	
P14.9	N5	51	36	AN/DAC/DIG_IN	
P14.12	L1	34	23	AN/DIG_IN	
P14.13	K4	33	22	AN/DIG_IN	

Table 12 Port I/O Functions (cont’d)

Function	Outputs						Inputs									
	ALT1	**ALT2**	**ALT3**	**ALT4**	**HWO0**	**HWO1**	**HWI0**	**HWI1**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**	**Input**
P4.3	U2C1. SELO2	U0C0. SELO5	CCU43. OUT3	ECAT0. MCLK									CCU43. IN3A			
P4.4		U0C0. SELO4	CCU43. OUT2		U2C1. DOUT3		U2C1. HWIN3						CCU43. IN2A			
P4.5		U0C0. SELO3	CCU43. OUT1		U2C1. DOUT2		U2C1. HWIN2						CCU43. IN1A			
P4.6		U0C0. SELO2	CCU43. OUT0		U2C1. DOUT1		U2C1. HWIN1		CAN. N2_RXDC			U2C1. DX0E	CCU43. IN0A			
P4.7	U2C1. DOUT0	CAN. N2_TXD			U2C1. DOUT0		U2C1. HWIN0		U0C0. DX0C				CCU43. IN0C			
P5.0	U2C0. DOUT0	DSD. CGPWMN	CCU81. OUT33	ERU1. PDOUT0	U2C0. DOUT0		U2C0. HWIN0		U2C0. DX0B	ETH0. RXD0D	U0C0. DX0D	ECAT0. P0_RXD0B	CCU81. IN0A	CCU81. IN1A	CCU81. IN2A	CCU81. IN3A
P5.1	U0C0. DOUT0	DSD. CGPWMP	CCU81. OUT32	ERU1. PDOUT1	U2C0. DOUT1		U2C0. HWIN1		U2C0. DX0A	ETH0. RXD1D		ECAT0. P0_RXD1B	CCU81. IN0B			
P5.2	U2C0. SCLKOUT	ECAT0. P0_LINK_ACT	CCU81. OUT23	ERU1. PDOUT2					U2C0. DX1A	ETH0. CRS_DVD		ECAT0. P0_RXD2B	CCU81. IN1B			ETH0. RXDVD
P5.3	U2C0. SELO0		CCU81. OUT22	ERU1. PDOUT3	EBU. CKE	EBU. A20			U2C0. DX2A	ETH0. RXERD			CCU81. IN2B			
P5.4	U2C0. SELO1		CCU81. OUT13		EBU. RAS	EBU. A21				ETH0. CRSD			CCU81. IN3B			ECAT0. P0_RX_CLKB
P5.5	U2C0. SELO2		CCU81. OUT12		EBU. CAS	EBU. A22				ETH0. COLD						ECAT0. P0_TX_CLKB
P5.6	U2C0. SELO3		CCU81. OUT03		EBU. BFCLKO	EBU. A23			EBU. BFCLKI							ECAT0. P0_RX_DVB
P5.7	ECAT0. SYNC0		CCU81. OUT02	LEDTS0. COLA	U2C0. DOUT2		U2C0. HWIN2					ECAT0. P0_RXD3B				
P5.8	ECAT0. P1_TX_ENA	U1C0. SCLKOUT	CCU80. OUT01	CAN. N4_TXD	EBU. SDCLKO	EBU. CS2			ETH0. RXD2A	U1C0. DX1B						
P5.9		U1C0. SELO0	CCU80. OUT20	ETH0. TX_EN	EBU. BFCLKO	EBU. CS3			ETH0. RXD3A	U1C0. DX2B					ECAT0. P1_TX_CLKB	
P5.10		U1C0. MCLKOUT	CCU80. OUT10	LEDTS0. LINE7	LEDTS0. EXTENDED7		LEDTS0. TSIN7A		ETH0. CLK_TXA		CAN. N5_RXDA					
P5.11		U1C0. SELO1	CCU80. OUT00	CAN. N5_TXD					ETH0. CRSA							
P6.0	ETH0. TXD2	U0C1. SELO1	CCU81. OUT31	ECAT0. PHY_CLK25	DB. ETM_TRACECLK	EBU. A16										
P6.1	ETH0. TXD3	U0C1. SELO0	CCU81. OUT30	ECAT0. P0_TX_ENA	DB. ETM_TRACEDATA3	EBU. A17			U0C1. DX2C							
P6.2	ETH0. TXER	U0C1. SCLKOUT	CCU43. OUT3	ECAT0. P0_TXD0	DB. ETM_TRACEDATA2	EBU. A18			U0C1. DX1C							
P6.3			CCU43. OUT2	ECAT0. P0_LINK_ACT					U0C1. DX0C	ETH0. RXD3B						
P6.4		U0C1. DOUT0	CCU43. OUT1	ECAT0. P0_TXD1	EBU. SDCLKO	EBU. A19			EBU. SDCLKI	ETH0. RXD2B						
P6.5	CAN. N3_TXD	U0C1. MCLKOUT	CCU43. OUT0	ECAT0. P0_TXD2	DB. ETM_TRACEDATA1	EBU. BC2			DSD. DIN3A	ETH0. CLK_RMIID		U2C0. DX0D				ETH0. CLKRXD

2.3 Power Connection Scheme

Figure 9. shows a reference power connection scheme for the XMC4[78]00.

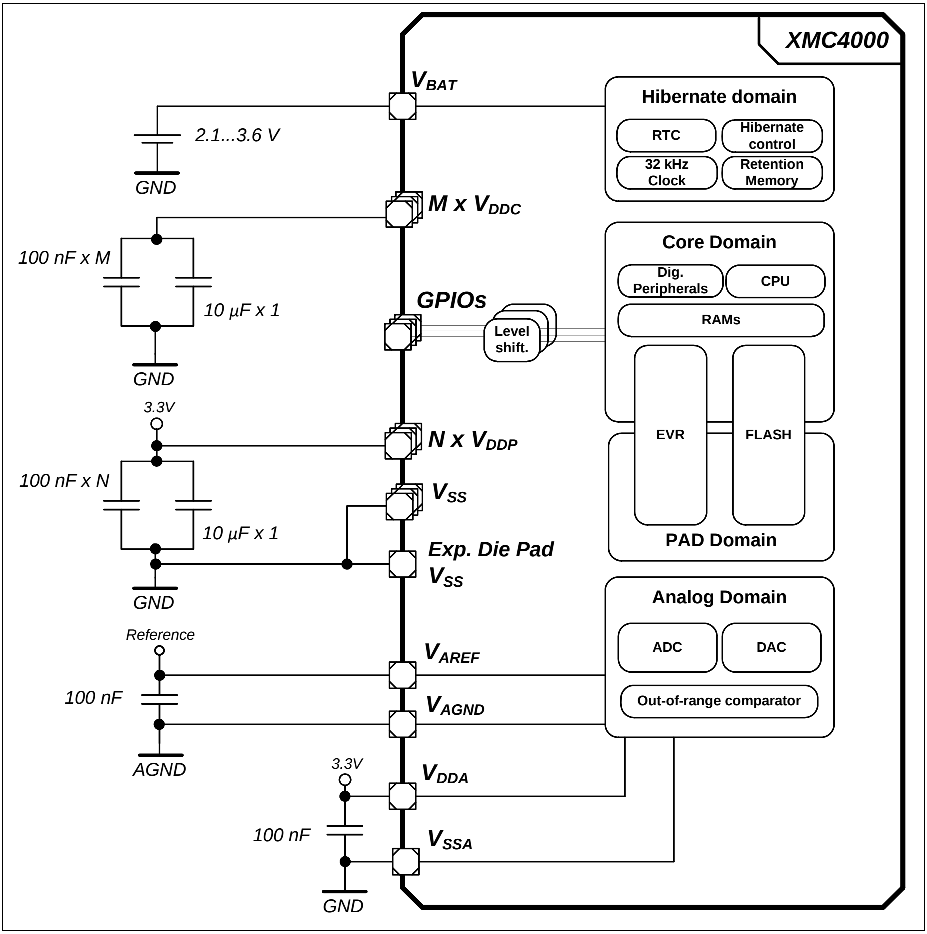

Figure 9 Power Connection Scheme

Every power supply pin needs to be connected. Different pins of the same supply need also to be externally connected. As example, all V_{DDP} pins must be connected externally to one V_{DDP} net. In this reference scheme one 100 nF capacitor is connected at each supply pin against V_{SS}. An additional 10 µF capacitor is connected to the V_{DDP} nets and an additional 10 uF capacitor to the V_{DDC} nets.

3.1.4 Pad Driver and Pad Classes Summary

This section gives an overview on the different pad driver classes and their basic characteristics.

Table 18 Pad Driver and Pad Classes Overview

Class	Power Supply	Type	Sub-Class	Speed Grade	Load	Termination
A	3.3 V	LVTTL I/O	**A1** (e.g. GPIO)	6 MHz	100 pF	No
			A1+ (e.g. serial I/Os)	25 MHz	50 pF	Series termination recommended
			A2 (e.g. ext. Bus)	80 MHz	15 pF	Series termination recommended

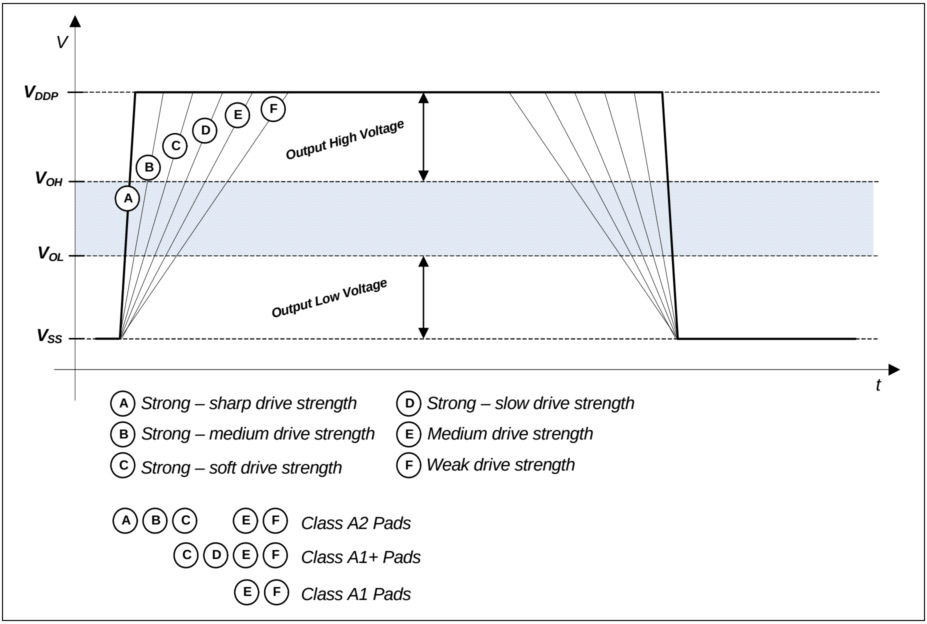

Figure 12 Output Slopes with different Pad Driver Modes

Figure 12 is a qualitative display of the resulting output slope performance with different output driver modes. The detailed input and output characteristics are listed in Section 3.2.1.

Table 22 Standard Pads Class_A1+

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.		Max.		
Output high voltage, POD[1] = weak	V_{OHA1+} CC	V_{DDP} - 0.4		–	V	$I_{OH} \geq$ -400 μA
		2.4		–	V	$I_{OH} \geq$ -500 μA
Output high voltage, POD[1] = medium		V_{DDP} - 0.4		–	V	$I_{OH} \geq$ -1.4 mA
		2.4		–	V	$I_{OH} \geq$ -2 mA
Output high voltage, POD[1] = strong		V_{DDP} - 0.4		–	V	$I_{OH} \geq$ -1.4 mA
		2.4		–	V	$I_{OH} \geq$ -2 mA
Output low voltage	V_{OLA1+} CC	–		0.4	V	$I_{OL} \leq$ 500 μA; POD[1] = weak
		–		0.4	V	$I_{OL} \leq$ 2 mA; POD[1] = medium
		–		0.4	V	$I_{OL} \leq$ 2 mA; POD[1] = strong
Fall time	t_{FA1+} CC	–		150	ns	C_L = 20 pF; POD[1] = weak
		–		50	ns	C_L = 50 pF; POD[1] = medium
		–		28	ns	C_L = 50 pF; POD[1] = strong; edge = slow
		–		16	ns	C_L = 50 pF; POD[1] = strong; edge = soft;
Rise time	t_{RA1+} CC	–		150	ns	C_L = 20 pF; POD[1] = weak
		–		50	ns	C_L = 50 pF; POD[1] = medium
		–		28	ns	C_L = 50 pF; POD[1] = strong; edge = slow
		–		16	ns	C_L = 50 pF; POD[1] = strong; edge = soft

1) POD = Pin Out Driver

Table 24 HIB_IO Class_A1 special Pads

Parameter	Symbol	Values		Unit	Note / Test Condition
		Min.	Max.		
Input leakage current	I_{OZHIB} CC	-500	500	nA	$0 V \leq V_{IN} \leq V_{BAT}$
Input high voltage	V_{IHHIB} SR	$0.6 \times V_{BAT}$	$V_{BAT} + 0.3$	V	max. 3.6 V
Input low voltage	V_{ILHIB} SR	-0.3	$0.36 \times V_{BAT}$	V	
Input Hysteresis for HIB_IO pins[1)]	$HYSHIB$ CC	$0.1 \times V_{BAT}$	–	V	$V_{BAT} \geq 3.13$ V
		$0.06 \times V_{BAT}$	–	V	$V_{BAT} < 3.13$ V
Output high voltage, POD[1)] = medium	V_{OHHIB} CC	V_{BAT} - 0.4	–	V	$I_{OH} \geq$ -1.4 mA
Output low voltage	V_{OLHIB} CC	–	0.4	V	$I_{OL} \leq 2$ mA
Fall time	t_{FHIB} CC	–	50	ns	$V_{BAT} \geq 3.13$ V $C_L = 50$ pF
		–	100	ns	$V_{BAT} < 3.13$ V $C_L = 50$ pF
Rise time	t_{RHIB} CC	–	50	ns	$V_{BAT} \geq 3.13$ V $C_L = 50$ pF
		–	100	ns	$V_{BAT} < 3.13$ V $C_L = 50$ pF

1) Hysteresis is implemented to avoid metastable states and switching due to internal ground bounce. It can not be guaranteed that it suppresses switching due to external system noise.

3.2.2 Analog to Digital Converters (VADC)

Note: These parameters are not subject to production test, but verified by design and/or characterization.

Table 25 VADC Parameters (Operating Conditions apply)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Analog reference voltage[5]	V_{AREF} SR	V_{AGND} + 1	–	V_{DDA} + 0.05[1]	V	
Analog reference ground[5]	V_{AGND} SR	V_{SSM} - 0.05	–	V_{AREF} - 1	V	
Analog reference voltage range[2)5]	V_{AREF} - V_{AGND} SR	1	–	V_{DDA} + 0.1	V	
Analog input voltage	V_{AIN} SR	V_{AGND}	–	V_{DDA}	V	
Input leakage at analog inputs[3]	I_{OZ1} CC	-100	–	200	nA	$0.03 \times V_{DDA} < V_{AIN} < 0.97 \times V_{DDA}$
		-500	–	100	nA	$0\ V \leq V_{AIN} \leq 0.03 \times V_{DDA}$
		-100	–	500	nA	$0.97 \times V_{DDA} \leq V_{AIN} \leq V_{DDA}$
Input leakage current at VAREF	I_{OZ2} CC	-1	–	1	µA	$0\ V \leq V_{AREF} \leq V_{DDA}$
Input leakage current at VAGND	I_{OZ3} CC	-1	–	1	µA	$0\ V \leq V_{AGND} \leq V_{DDA}$
Internal ADC clock	f_{ADCI} CC	2	–	36	MHz	V_{DDA} = 3.3 V
Switched capacitance at the analog voltage inputs[4]	C_{AINSW} CC	–	4	6.5	pF	
Total capacitance of an analog input	C_{AINTOT} CC	–	12	20	pF	
Switched capacitance at the positive reference voltage input[5)6]	C_{AREFSW} CC	–	15	30	pF	
Total capacitance of the voltage reference inputs[5]	$C_{AREFTOT}$ CC	–	20	40	pF	

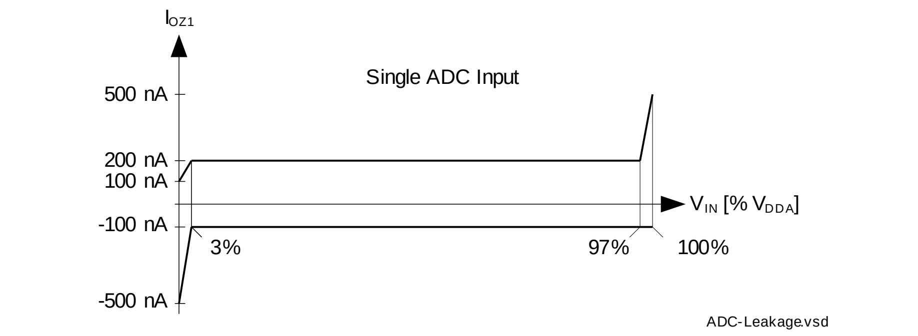

Figure 16 VADC Analog Input Leakage Current

Conversion Time

Table 26 Conversion Time (Operating Conditions apply)

Parameter	Symbol		Values	Unit	Note
Conversion time	t_C	CC	$2 \times T_{ADC}$ + (2 + N + STC + PC +DM) $\times$ T_{ADCI}	µs	N = 8, 10, 12 for N-bit conversion $T_{ADC} = 1 / f_{PERIPH}$ $T_{ADCI} = 1 / f_{ADCI}$

- STC defines additional clock cycles to extend the sample time
- PC adds two cycles if post-calibration is enabled
- DM adds one cycle for an extended conversion time of the MSB

Conversion Time Examples

System assumptions:
f_{ADC} = 144 MHz i.e. t_{ADC} = 6.9 ns, DIVA = 3, f_{ADCI} = 36 MHz i.e. t_{ADCI} = 27.8 ns

According to the given formulas the following minimum conversion times can be achieved (STC = 0, DM = 0):

12-bit post-calibrated conversion (PC = 2):
$t_{CN12C} = (2 + 12 + 2) \times t_{ADCI} + 2 \times t_{ADC} = 16 \times 27.8$ ns $+ 2 \times 6.9$ ns = 459 ns

12-bit uncalibrated conversion:
$t_{CN12} = (2 + 12) \times t_{ADCI} + 2 \times t_{ADC} = 14 \times 27.8$ ns $+ 2 \times 6.9$ ns = 403 ns

10-bit uncalibrated conversion:
$t_{CN10} = (2 + 10) \times t_{ADCI} + 2 \times t_{ADC} = 12 \times 27.8$ ns $+ 2 \times 6.9$ ns = 348 ns

8-bit uncalibrated:
$t_{CN8} = (2 + 8) \times t_{ADCI} + 2 \times t_{ADC} = 10 \times 27.8$ ns $+ 2 \times 6.9$ ns = 292 ns

Table 31 USB OTG Data Line (USB_DP, USB_DM) Parameters (Operating Conditions apply)

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
Input low voltage	V_{IL}	SR	–	–	0.8	V	
Input high voltage (driven)	V_{IH}	SR	2.0	–	–	V	
Input high voltage (floating) [1]	V_{IHZ}	SR	2.7	–	3.6	V	
Differential input sensitivity	V_{DIS}	CC	0.2	–	–	V	
Differential common mode range	V_{CM}	CC	0.8	–	2.5	V	
Output low voltage	V_{OL}	CC	0.0	–	0.3	V	1.5 kOhm pull-up to 3.6 V
Output high voltage	V_{OH}	CC	2.8	–	3.6	V	15 kOhm pull-down to 0 V
DP pull-up resistor (idle bus)	R_{PUI}	CC	900	–	1 575	Ohm	
DP pull-up resistor (upstream port receiving)	R_{PUA}	CC	1 425	–	3 090	Ohm	
DP, DM pull-down resistor	R_{PD}	CC	14.25	–	24.8	kOhm	
Input impedance DP, DM	Z_{INP}	CC	300	–	–	kOhm	$0\ V \leq V_{IN} \leq V_{DDP}$
Driver output resistance DP, DM	Z_{DRV}	CC	28	–	44	Ohm	

1) Measured at A-connector with 1.5 kOhm ± 5% to 3.3 V ± 0.3 V connected to USB_DP or USB_DM and at B-connector with 15 kOhm ± 5% to ground connected to USB_DP and USB_DM.

3.2.8 Power Supply Current

The total power supply current defined below consists of a leakage and a switching component.

Application relevant values are typically lower than those given in the following tables, and depend on the customer's system operating conditions (e.g. thermal connection or used application configurations).

Note: These parameters are not subject to production test, but verified by design and/or characterization.

If not stated otherwise, the operating conditions for the parameters in the following table are:
V_{DDP} = 3.3 V, T_A = 25 °C

Table 34 Power Supply Parameters

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
Active supply current[1)11)] Peripherals enabled Frequency: f_{CPU} / f_{PERIPH} / f_{CCU} in MHz	I_{DDPA}	CC	–	135	–	mA	144 / 144 / 144
			–	125	–		144 / 72 / 72
			–	97	–		72 / 72 / 144
			–	80	–		24 / 24 / 24
			–	68	–		1 / 1 / 1
Active supply current Code execution from RAM Flash in Sleep mode	I_{DDPA}	CC	–	108	–	mA	144 / 144 / 144
			–	98	–		144 / 72 / 72
Active supply current[2)] Peripherals disabled Frequency: f_{CPU} / f_{PERIPH} / f_{CCU} in MHz	I_{DDPA}	CC	–	86	–	mA	144 / 144 / 144
			–	85	–		144 / 72 / 72
			–	70	–		72 / 72 / 144
			–	55	–		24 / 24 / 24
			–	50	–		1 / 1 / 1
Sleep supply current[3)] Peripherals enabled Frequency: f_{CPU} / f_{PERIPH} / f_{CCU} in MHz	I_{DDPS}	CC	–	127	–	mA	144 / 144 / 144
			–	115	–		144 / 72 / 72
			–	93	–		72 / 72 / 144
			–	57	–		24 / 24 / 24
			–	47	–		1 / 1 / 1
f_{CPU} / f_{PERIPH} / f_{CCU} in kHz			–	48	–		100 / 100 / 100

3.3.4 Phase Locked Loop (PLL) Characteristics

Note: These parameters are not subject to production test, but verified by design and/or characterization.

Main and USB PLL

Table 39 PLL Parameters

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Accumulated Jitter	D_P CC	–	–	±5	ns	accumulated over 300 cycles f_{SYS} = 144 MHz
Duty Cycle[1]	D_{DC} CC	46	50	54	%	Low pulse to total period, assuming an ideal input clock source
PLL base frequency	$f_{PLLBASE}$ CC	30	–	140	MHz	
VCO input frequency	f_{REF} CC	4	–	16	MHz	
VCO frequency range	f_{VCO} CC	260	–	520	MHz	
PLL lock-in time	t_L CC	–	–	400	µs	

1) 50% for even K2 divider values, 50±(10/K2) for odd K2 divider values.

Write Timing

Table 58 Asynchronous Write Timing, Multiplexed and Demultiplexed

Parameter			Symbol	Limit Values		Unit
				Min.	Max.	
A(24:0) output delay	to RD/$\overline{WR}$ rising edge, deviation from the ideal programmed value.	CC	t_{30}	-2.5	2.5	ns
A(24:0) output delay		CC	t_{31}	-2.5	2.5	
$\overline{CS}$ rising edge		CC	t_{32}	-2	2	
$\overline{ADV}$ rising edge		CC	t_{33}	-2	4.5	
$\overline{BC}$ rising edge		CC	t_{34}	-2.5	2	
$\overline{WAIT}$ input setup		SR	t_{35}	12	–	
$\overline{WAIT}$ input hold		SR	t_{36}	0	–	
Data output delay		CC	t_{37}	-5.5	2	
Data output delay		CC	t_{38}	-5.5	2	
RD / $\overline{WR}$ output delay		CC	t_{39}	-2.5	1.5	

Multiplexed Write Timing

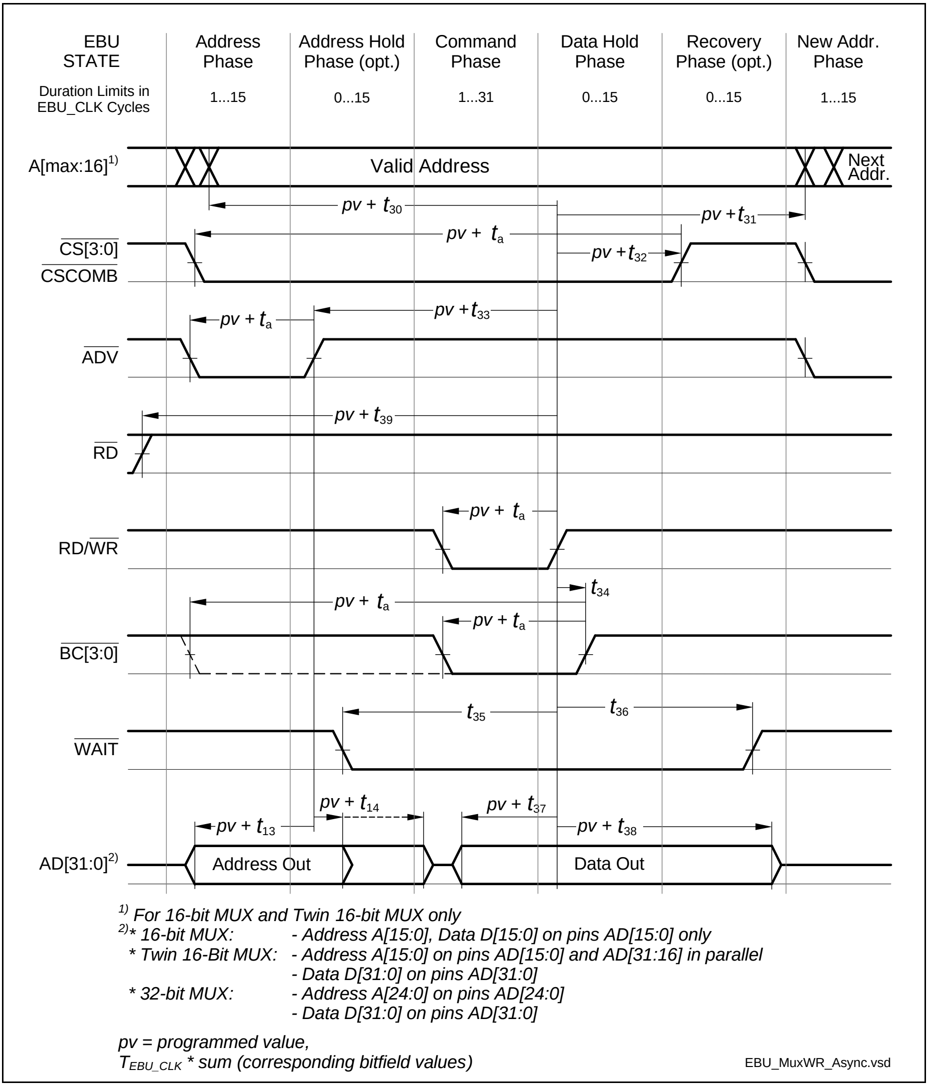

Figure 43 Multiplexed Write Access

3.3.10.3 EBU Arbitration Signal Timing

Note: These parameters are not subject to production test, but verified by design and/or characterization.

Note: Operating Conditions apply.

Table 60 EBU Arbitration Signal Timing Parameters

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
Output delay from BFCLKO rising edge	t_1	CC	–	–	16	ns	C_L = 50 pF
Data setup to BFCLKO falling edge	t_2	SR	11	–	–	ns	–
Data hold from BFCLKO falling edge	t_3	SR	2	–	–	ns	–

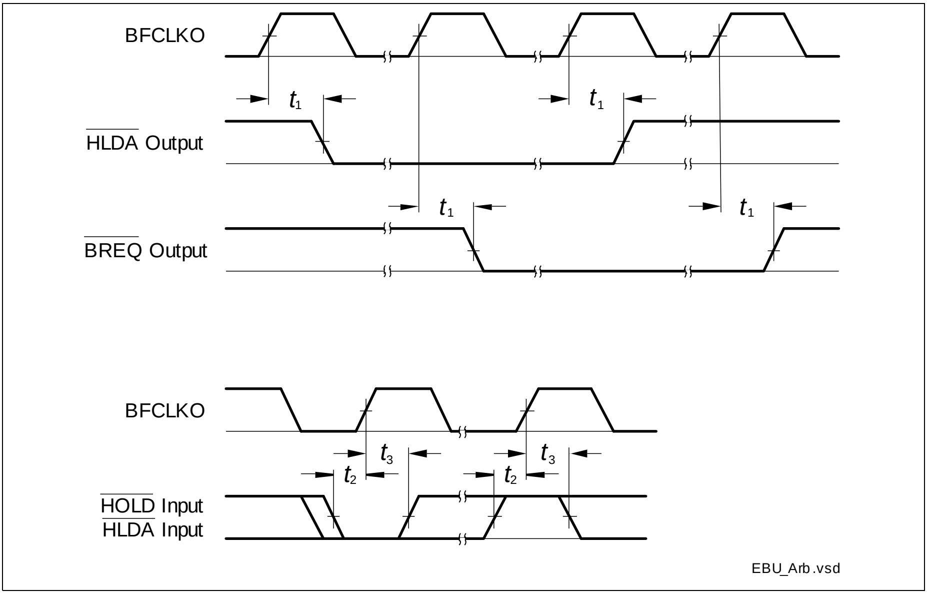

Figure 46 EBU Arbitration Signal Timing

Table 62 EBU SDRAM Access Signal Timing Parameters

Parameter			Symbol	Limit Values		Unit
				Min.	Max.	
A(15:0) output valid	from SDCLKO low-to-high transition	CC	t_6	–	9	ns
A(15:0) output hold		CC	t_7	3	–	
$\overline{\text{CS(3:0)}}$ low		CC	t_8	–	9	
$\overline{\text{CS(3:0)}}$ high		CC	t_9	3	–	
$\overline{\text{RAS}}$ low		CC	t_{10}	–	9	
$\overline{\text{RAS}}$ high		SR	t_{11}	3	–	
$\overline{\text{CAS}}$ low		SR	t_{12}	–	9	
$\overline{\text{CAS}}$ high		CC	t_{13}	3	–	
RD/$\overline{\text{WR}}$ low		CC	t_{14}	–	9	
RD/$\overline{\text{WR}}$ high		CC	t_{15}	3	–	
$\overline{\text{BC(3:0)}}$ low		CC	t_{16}	–	9	
$\overline{\text{BC(3:0)}}$ high		CC	t_{17}	3	–	
D(15:0) output valid		CC	t_{18}	–	9	
D(15:0) output hold		CC	t_{19}	3	–	
CKE output valid[1)]		CC	t_{22}	–	7	
CKE output hold[1)]		CC	t_{23}	2	–	
D(15:0) input hold		SR	t_{21}	3	–	
D(15:0) input setup to SDCLKO low-to-high transition		SR	t_{20}	4	–	

1) Not depicted in the read and write access timing figures below.

3.3.13.4 MII Timing RX Characteristics

Table 69 ETH MII RX Signal Timing Parameters

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
RX_CLK period	t_{RX_CLK}	SR	–	40	–	ns	C_L = 25 pF, IEEE802.3 requirement
RX_DV/RX_DV/RXD[3:0] valid before rising edge of RX_CLK	t_{RX_setup}	SR	10	–	–	ns	
RX_DV/RX_DV/RXD[3:0] valid after rising edge of RX_CLK	t_{RX_hold}	SR	10	–	–	ns	

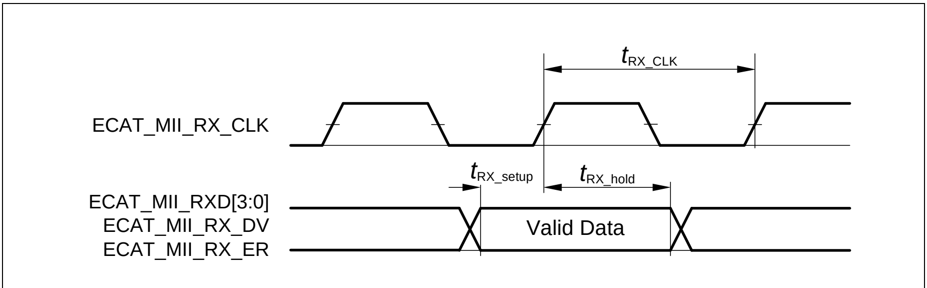

Figure 58 MII RX characteristics